Abstracts

A test board for multiport immittance measurement and characterization of RF-IC packages

A. Tripathi, R. Lutz, V.K. Tripathi, H.H. Wu, J.W. Meyer and B. Hutchison. "A test board for multiport immittance measurement and characterization of RF-IC packages." 1998 MTT-S International Microwave Symposium Digest 98.3 (1998 Vol. III [MWSYM]): 1921-1924.

An experimental technique based on the measurement of two port scattering parameters for the characterization of electrically small RF-IC package is presented. The procedure is based on a novel test board design to facilitate extraction of n-port admittance and impedance matrix parameters using two port network analyzer scattering parameter measurements. An optimization routine is used to extract the SPICE based equivalent circuit model that includes the mutual coupling effects present in the RF-IC package pins.

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